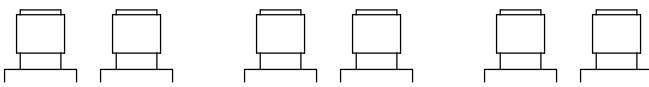




### **PRIMARY SILKSCREEN**



1

CLKIN

15

CLKINE

## 10 VOLT TABLE

<b>SW2-1</b>	<b>SW2-2</b>	<b>SW2-3</b>	<b>VDD_IO</b>
OPEN	OPEN	OPEN	1.0V
<b>CLOSED</b>	OPEN	OPEN	1.2V
OPEN	<b>CLOSED</b>	OPEN	1.0V
OPEN	OPEN	<b>CLOSED</b>	1.0V

Pinout diagram for the VDD\_AUX pin (TP3):

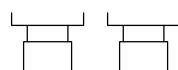
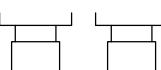
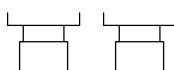
- EXT PWR**: Connected to Pin 1.
- +5V SELECT**: Connected to Pin 2.
- USB PWR**: Connected to Pin 3.
- GND**: Connected to Pin 4.
- SW1**: Connected to Pin 5.
- +5V**: Connected to Pin 6.
- GND**: Connected to Pin 7.
- JP2**: Jumper position between Pin 8 and Pin 9.
- JP3**: Jumper position between Pin 10 and Pin 11.
- JP4**: Jumper position between Pin 12 and Pin 13.
- JP5**: Jumper position between Pin 14 and Pin 15.
- JP6**: Jumper position between Pin 16 and Pin 17.
- JP7**: Jumper position between Pin 18 and Pin 19.
- GND**: Connected to Pin 20.
- SDA**: Connected to Pin 21.
- GND**: Connected to Pin 22.

 **SILICON LABS**  
SiLabs® Si53208-EVB  
8 - OUTPUT - QFN48  
REV 1.0 -



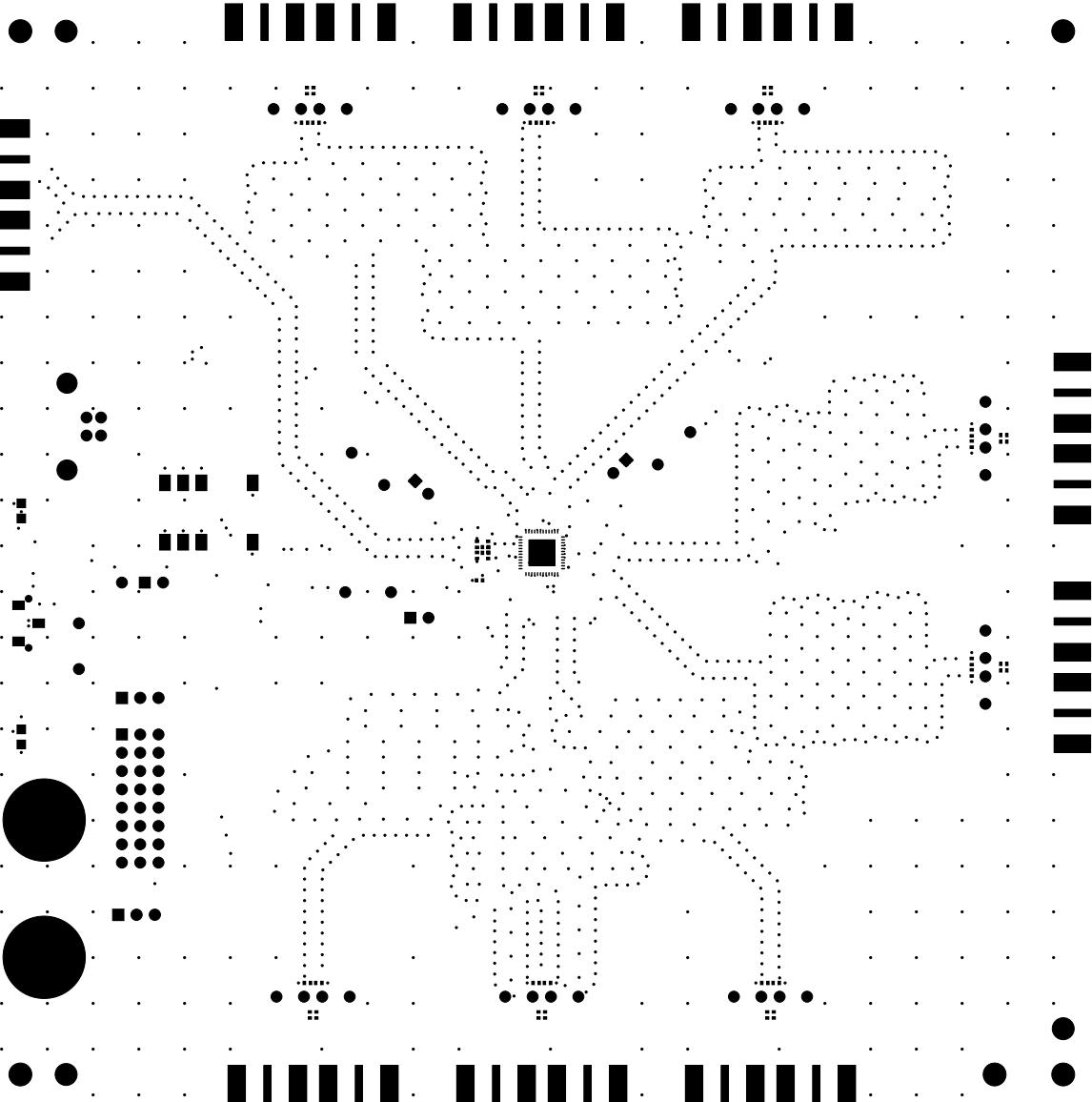
C43 C44  
**GND**      **GND**  
 R37 -- R39  
**DIFF\_0**      **DIFF\_0b**

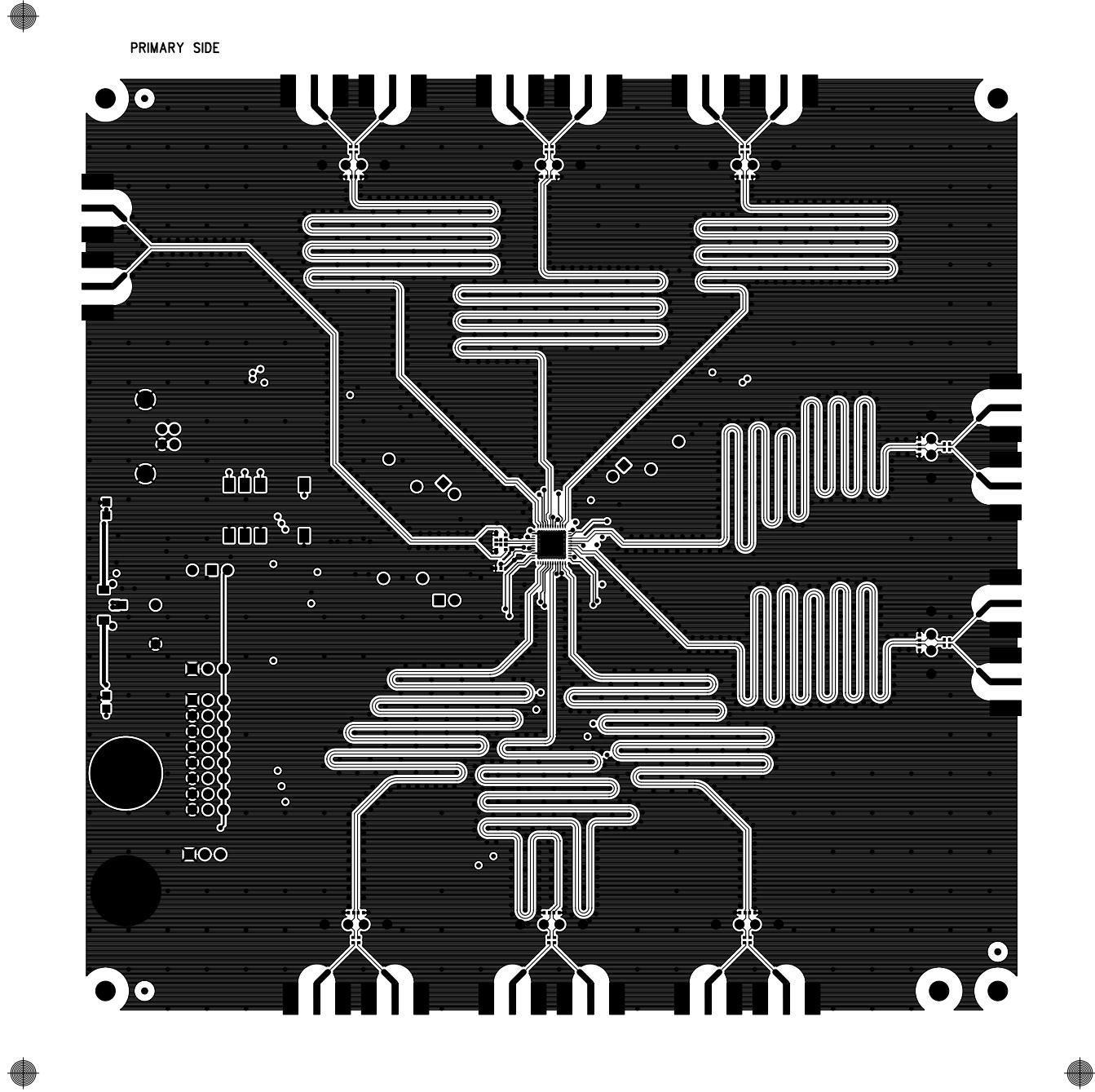
33  
GND GND  
M-3  
DIFF\_1 DIFF\_1b





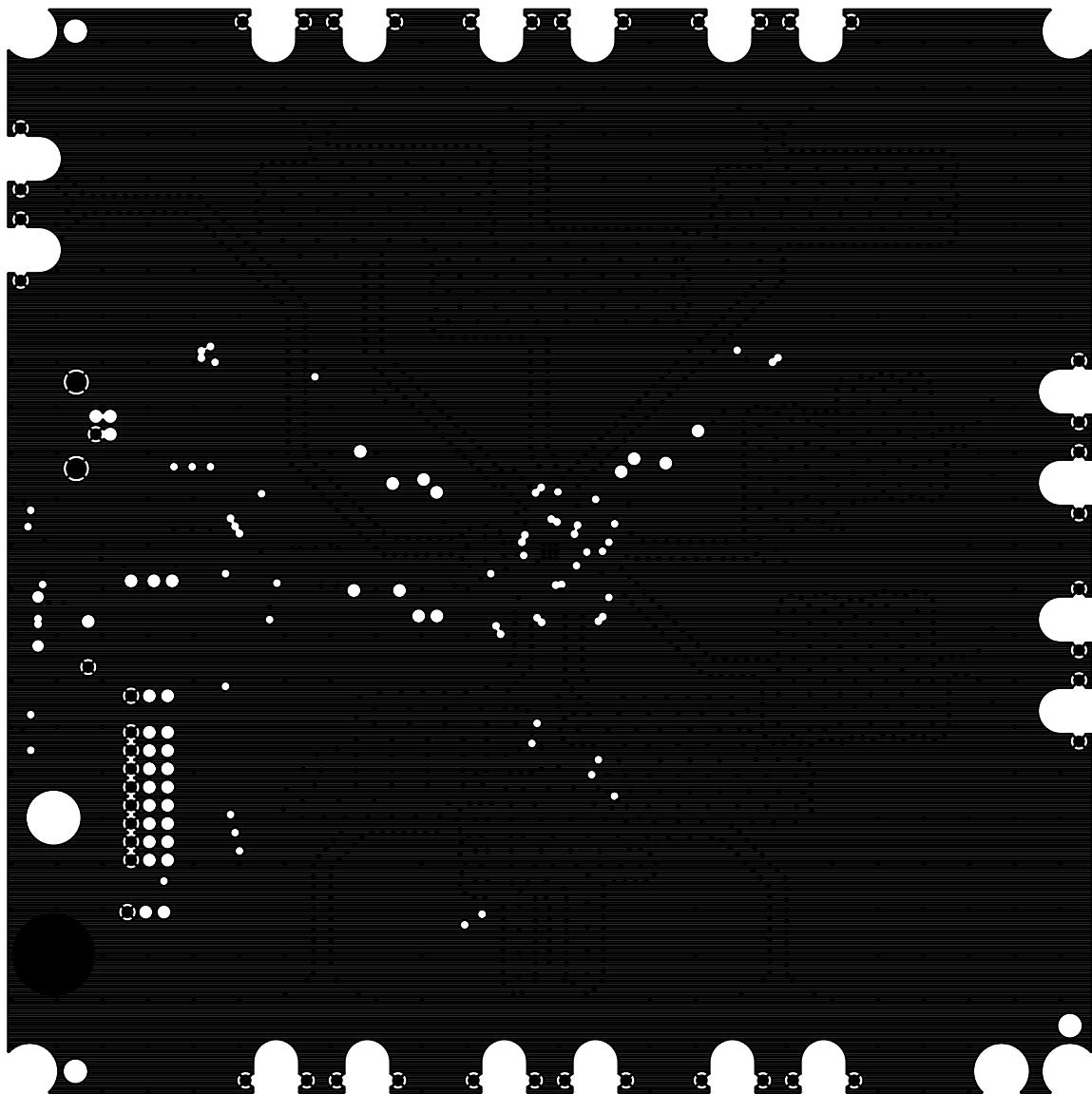
PRIMARY SOLDER MASK





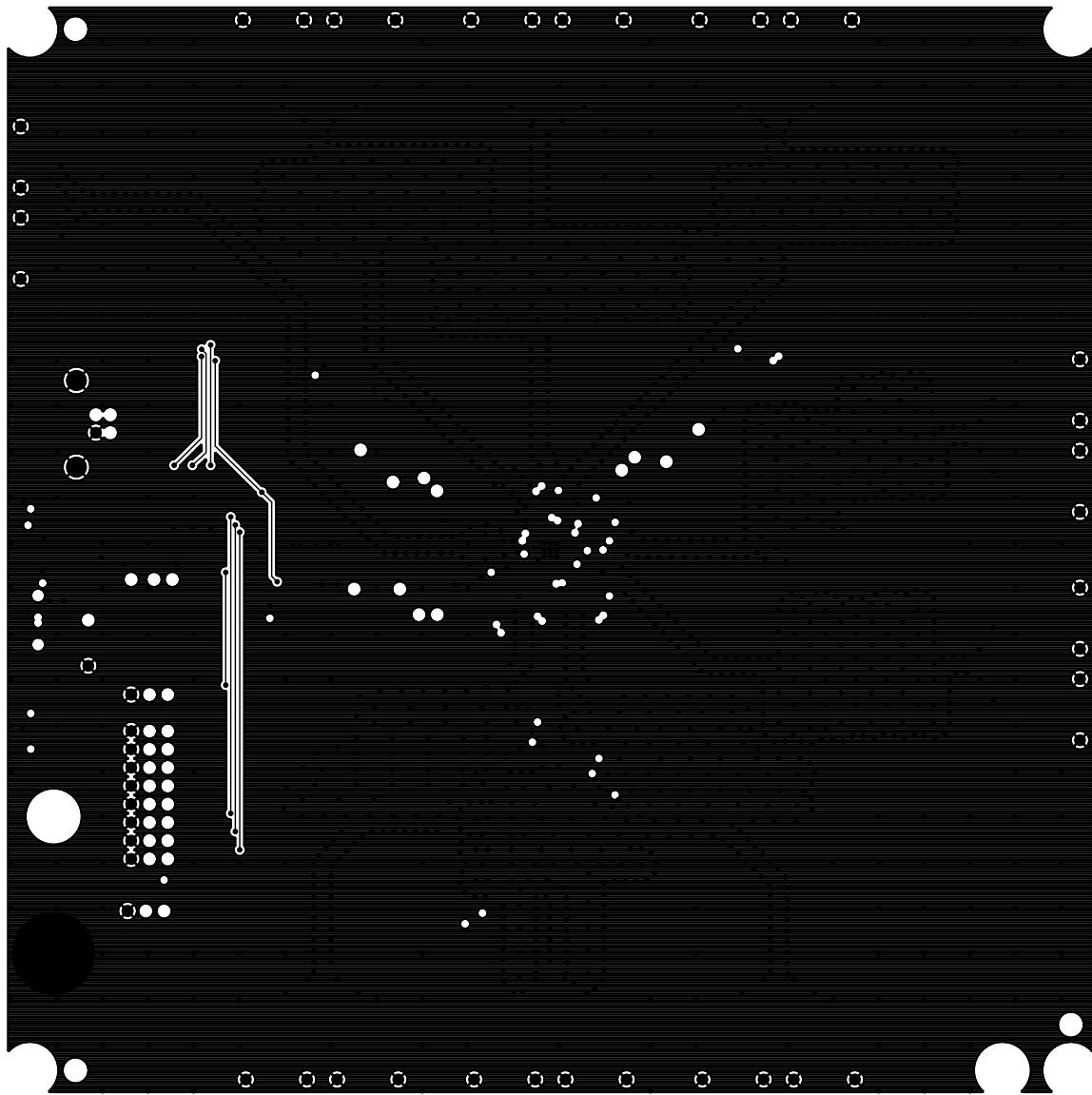


L02 (GROUND PLANE)

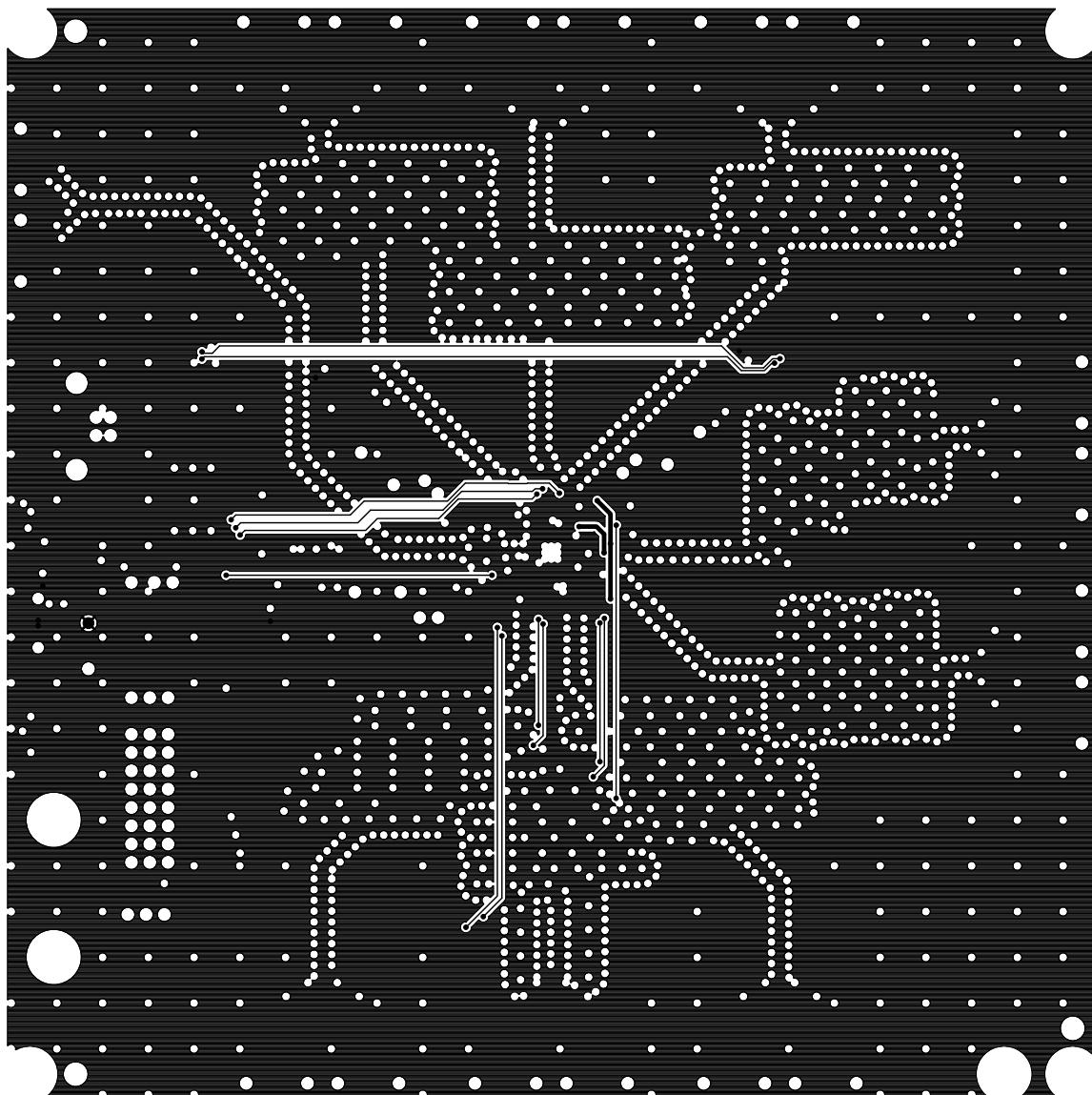




L03 (GROUND PLANE)

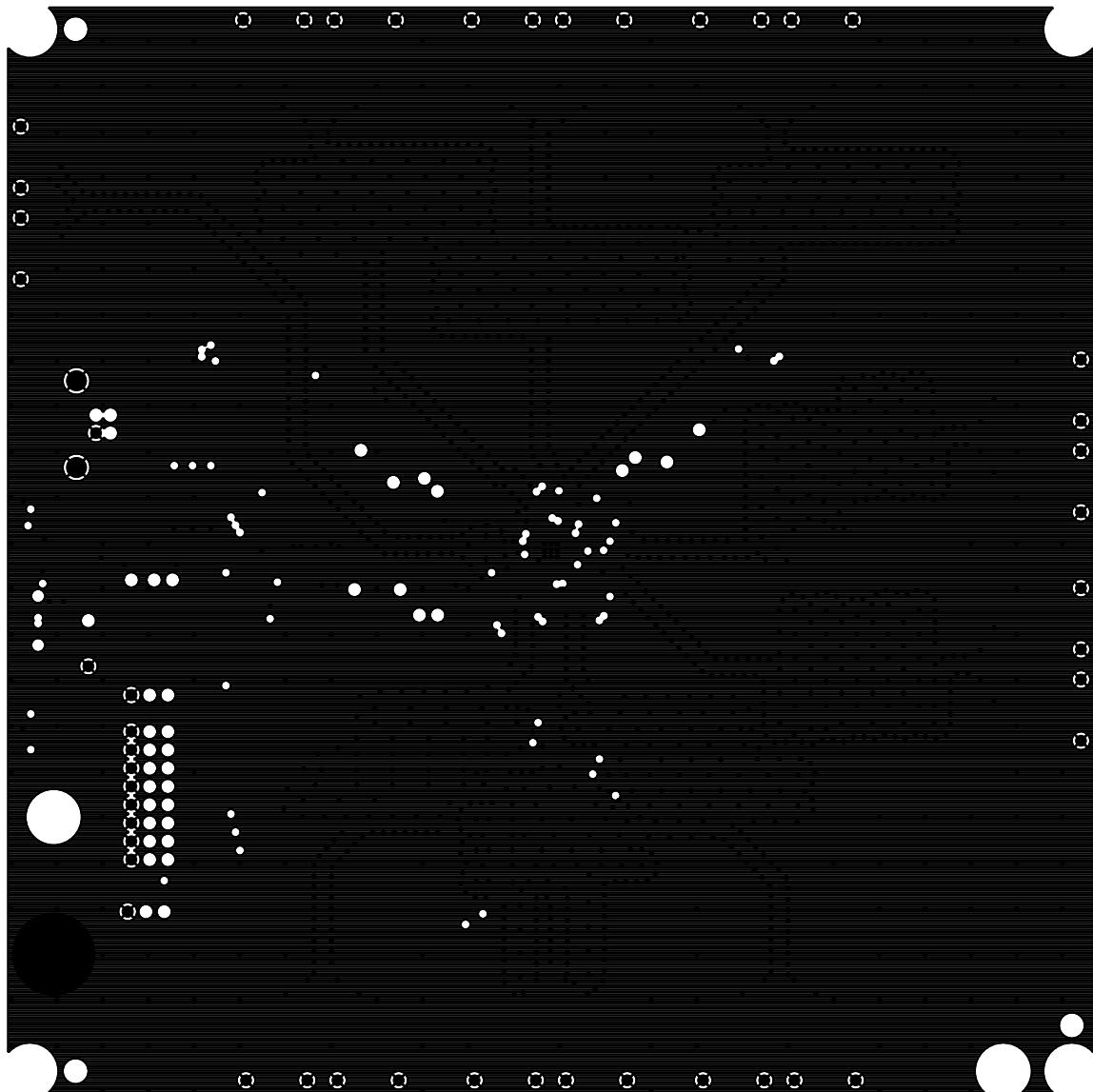


L04 (+5V/ROUTE)

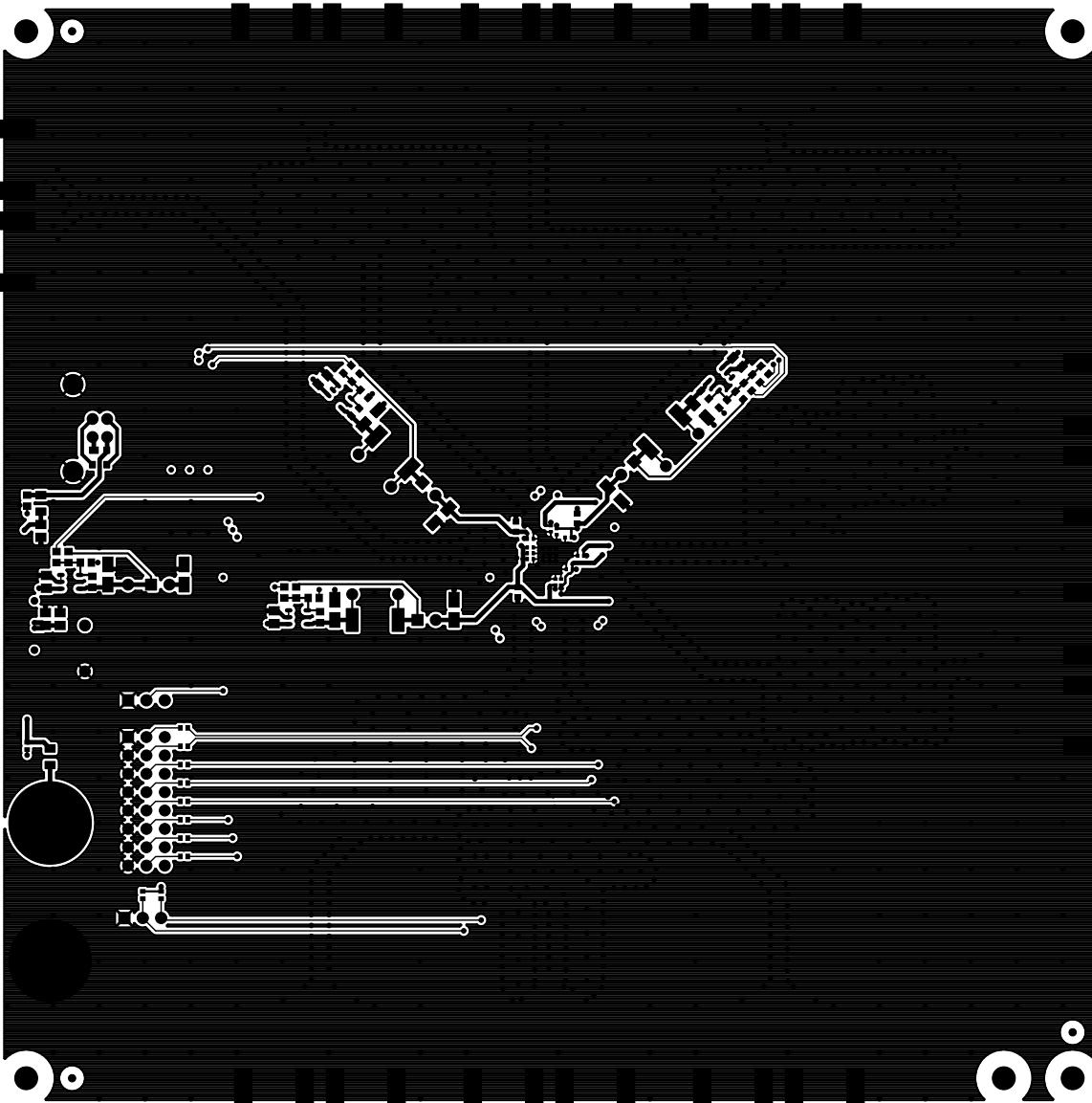




L05 (GROUND PLANE)

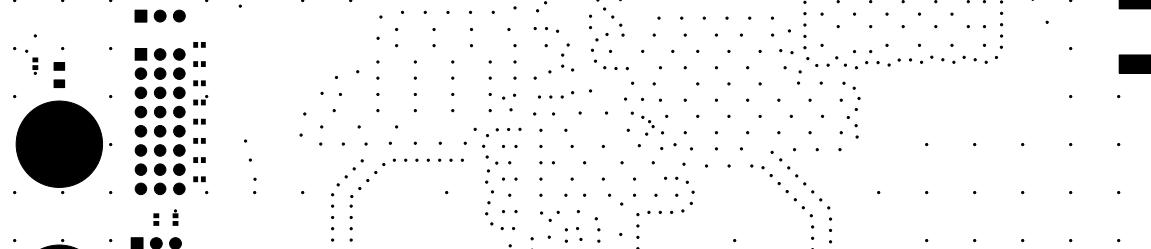
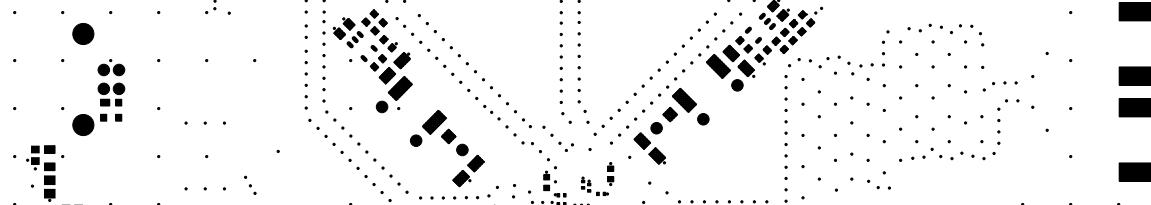
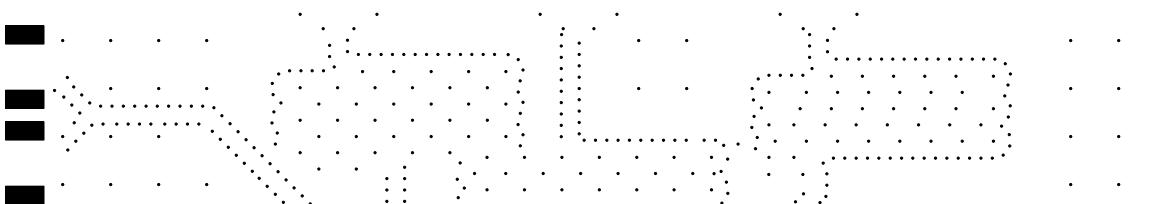


SECONDARY SIDE



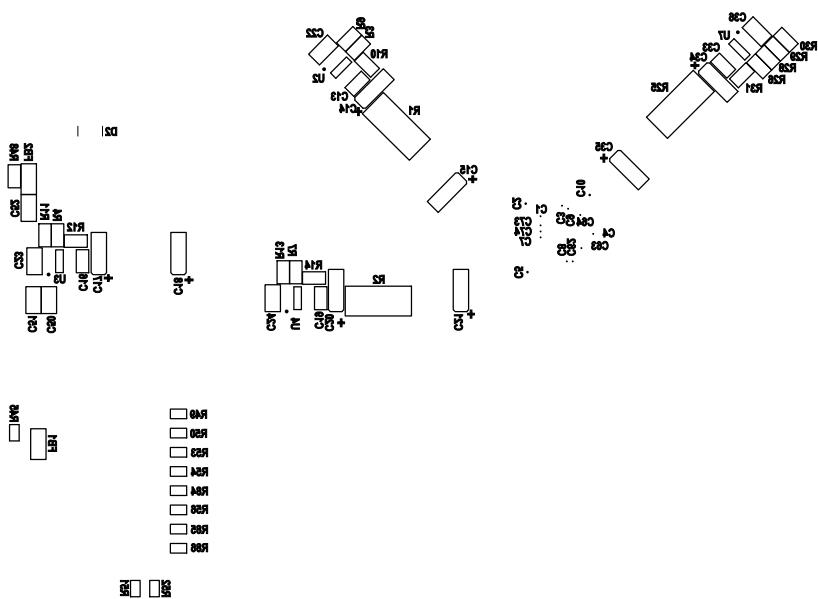


SECONDARY SOLDER MASK





SECONDARY SILKSCREEN





PRIMARY SOLDER PASTE

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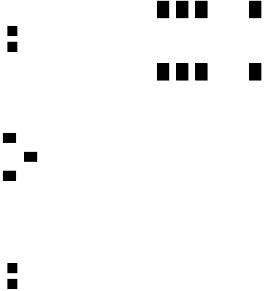
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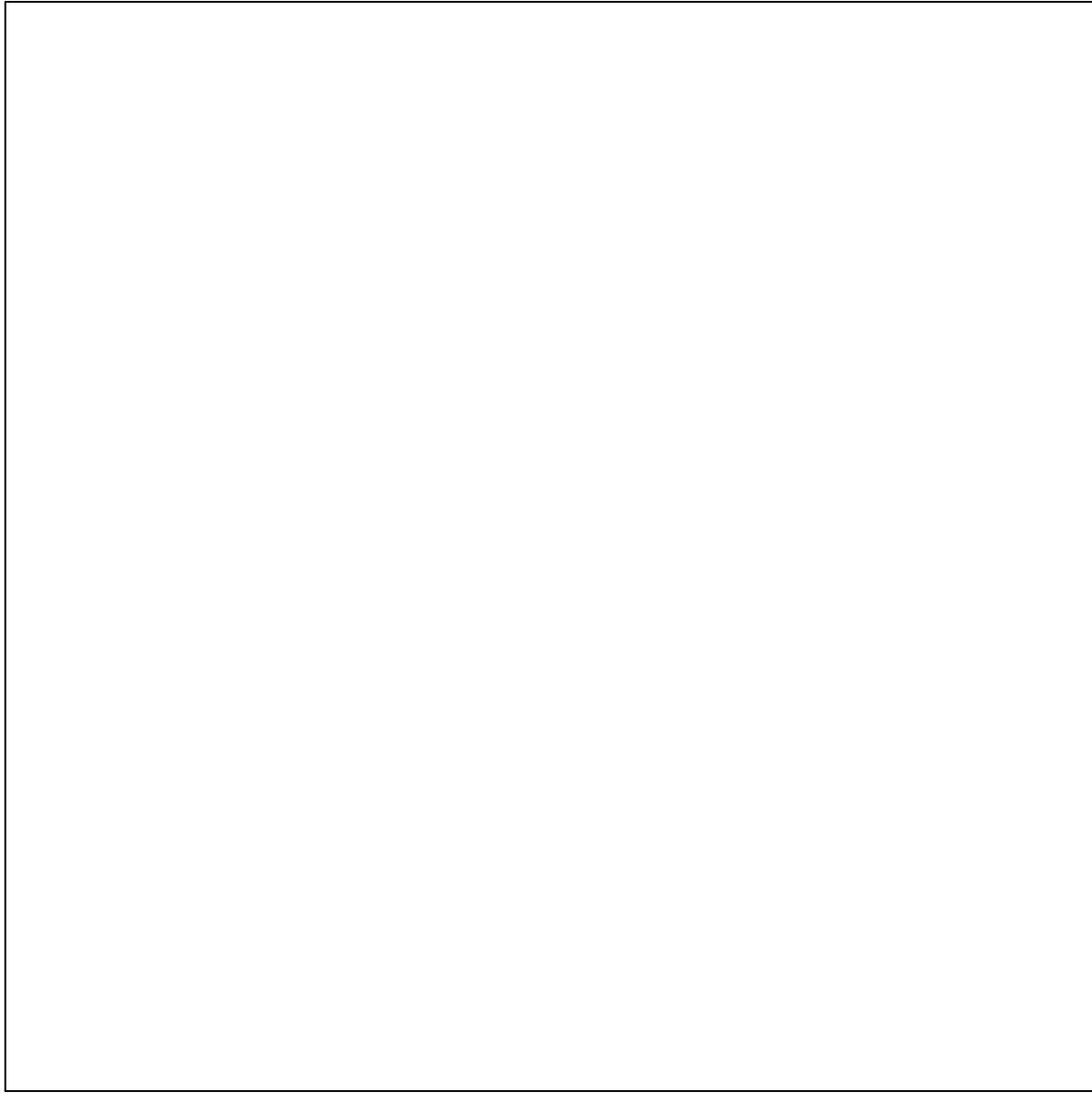
...

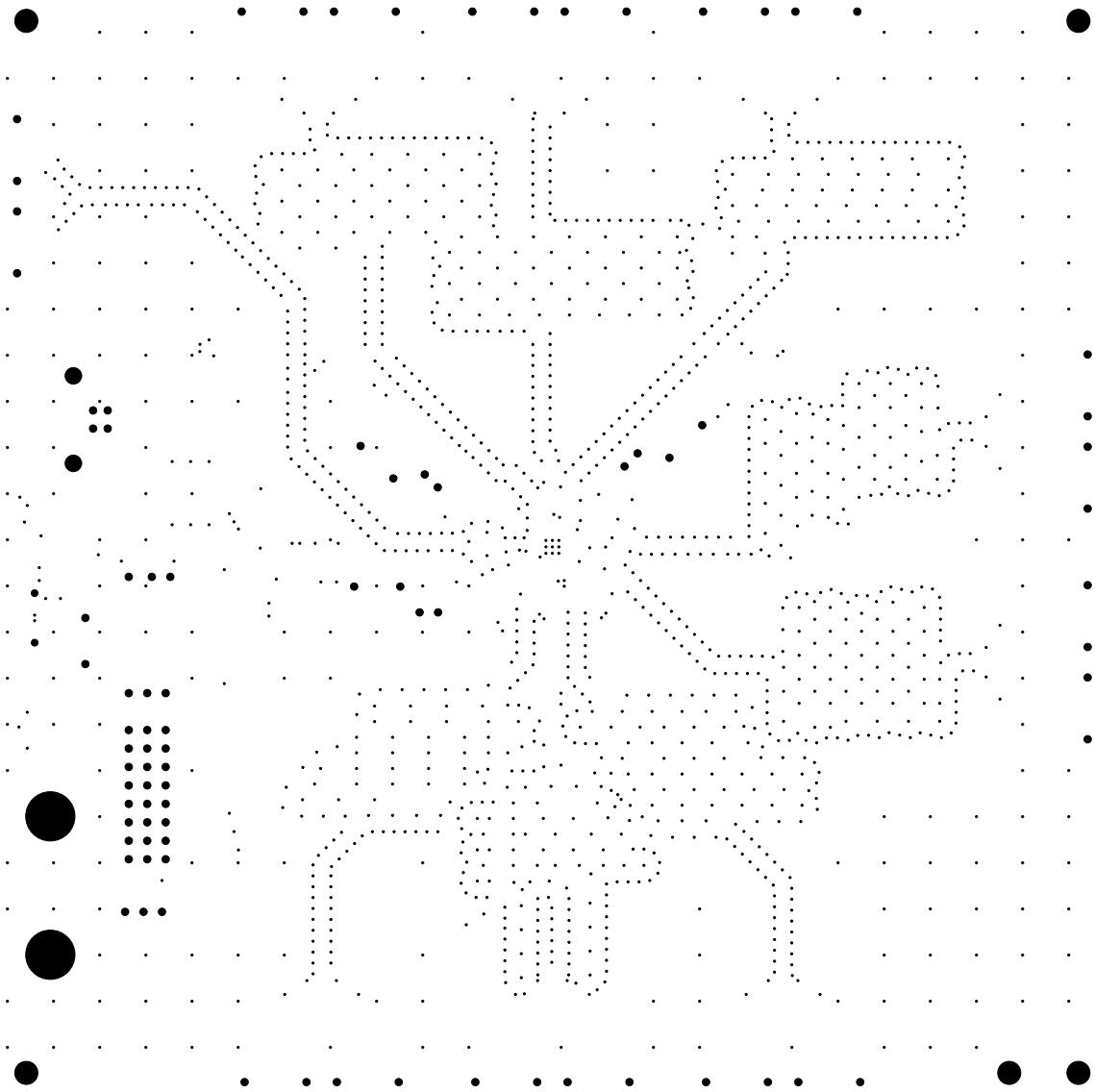




SECONDARY SOLDER PASTE



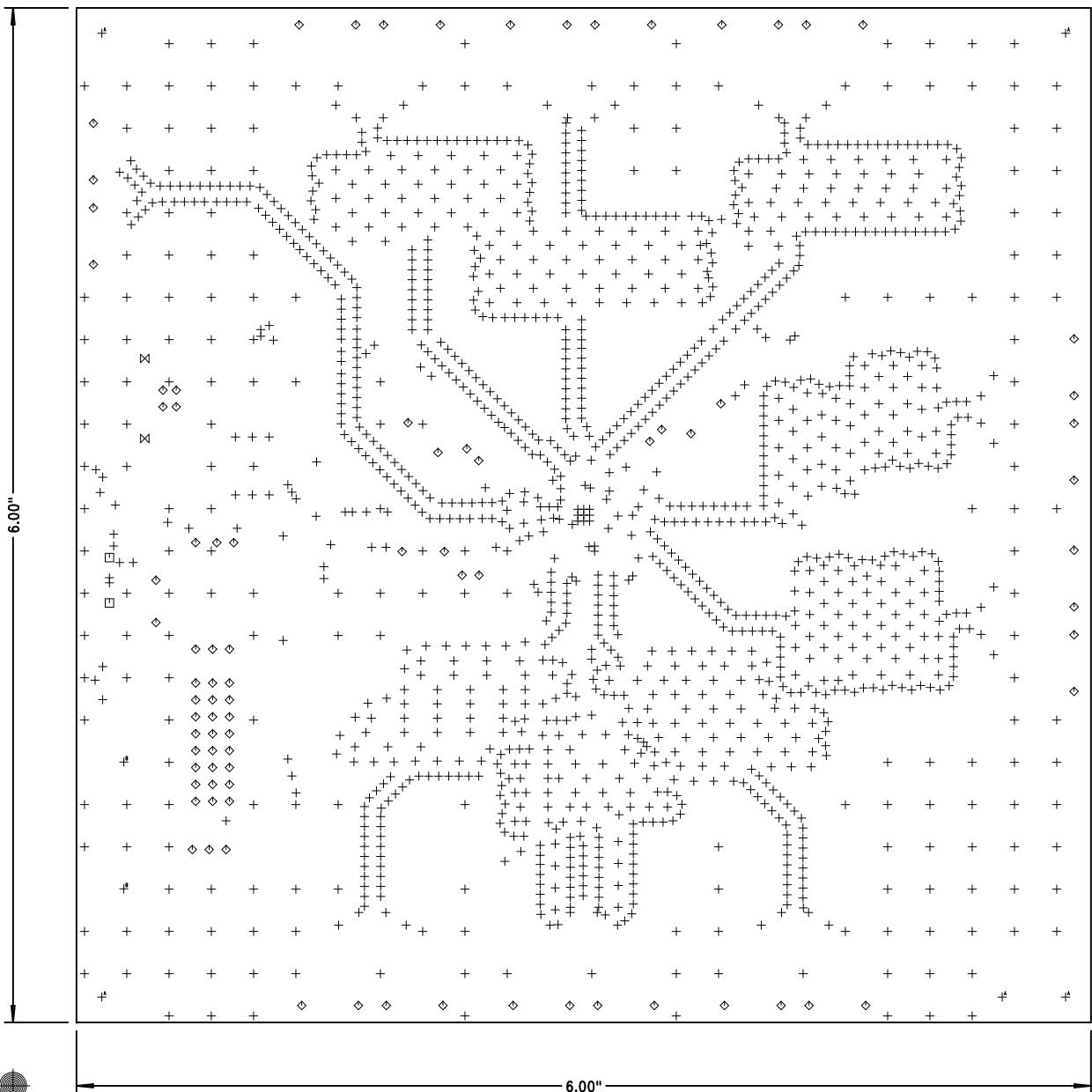




NOTES : UNLESS OTHERWISE SPECIFIED

1. MANUFACTURE IN ACCORDANCE WITH IPC-6012, TYPE 3, CLASS 2.
2. END PRODUCT FEATURES SHALL NOT VARY MORE THAN 20% FROM ARTWORK ORIGINALS.
3. LAMINATE AND PREPREG SHALL BE AS PER IPC-4101/26,83,98 WITH A DECOMPOSITION TEMPERATURE  $\geq 345^\circ\text{C}$ , COLOR, NATURAL.
4. COPPER WEIGHT SHALL BE 1.0 OZ./SQ. FT. BEFORE PLATING.
5. ALL PLATED THROUGH HOLES SHALL HAVE A MINIMUM OF 0.001" COPPER.
6. DRILL HOLE TOLERANCE AFTER PLATING SHALL BE  $\pm 0.003"$ .
7. MINIMUM ANNULAR RING SHALL BE 0.001".
8. MINIMUM ANNULAR RING AT EMERGENT CONDUCTORS SHALL BE 0.003".
9. FINAL PCB THICKNESS SHALL BE 0.062"  $\pm 10\%$ .
10. WARP/TWIST SHALL NOT EXCEED 1.0%
11. FINISH SHALL BE LPI, BLUE S.M.O.B.C., BALANCE ENIG.
12. SILKSCREEN WITH NONCONDUCTIVE WHITE EPOXY INK.
13. VENDOR TO PROVIDE PCB MICRO-SECTION OF COUPON AREA & TDR TEST REPORT.
14. REFERENCE ADDITIONAL FAB NOTES IN FILE README.TXT

PRIMARY DRILL



DO NOT ADJUST SPECIFIED GEOMETRIES WITHOUT NOTIFICATION.						
GERBER FILENAME	LAYER	SINGLE ENDED IMPEDANCE		DIFFERENTIAL IMPEDANCE		THICKNESS (INCH)
		IMPEDANCE (OHMS)	TRACE WIDTH (MM)	IMPEDANCE (OHMS)	TRACE WIDTH (MM)	
53208-CEVB_PSS.PHO	PRIMARY SILKSCREEN					
53208-CEVB_PSM.PHO	PRIMARY SOLDER MASK					
53208-CEVB_PRPHO_L01	PRIMARY (Signal)	50	0.15	100	0.15	0.35
53208-CEVB_L02.PHO_L02	PLANE (GND)	370HR				1.0 oz
53208-CEVB_L03.PHO_L03	PLANE (GND)	370HR				1.0 oz
53208-CEVB_L04.PHO_L04	PLANE (LVDS/ROUTE)	370HR				1.0 oz
53208-CEVB_L05.PHO_L05	PLANE (GND)	370HR				1.0 oz
53208-CEVB_SEC.PHO_L06	SECONDARY (Signal)	370HR				0.374 MIL
53208-CEVB_SSM.PHO	SECONDARY SOLDER MASK					
53200-CEVB_SSS.PHO	SECONDARY SILKSCREEN					

SIZE	QTY	SYM	PLT	TOOL	TOL
0.012	1551	+	P	1	+0/-0.012
0.034	2	X	N	2	+/-0.003
0.036	2	□	N	3	+/-0.003
0.040	87	◊	P	4	+/-0.003
0.064	4	☒	N	5	+/-0.003
0.091	2	☒	P	6	+/-0.003
0.125	7	A	N	7	+/-0.003
0.266	2	B	P	8	+/-0.003

UNLESS OTHERWISE SPECIFIED	COMPANY:	
DIMENSIONS ARE IN INCHES AND APPLY AFTER FINISH	 SILICON LABS	
INTERPRET DRAWING PER MIL-D-1000	400 W Cesar Chavez AUSTIN, TX 78701 (512)416-8500 <a href="http://www.silabs.com">www.silabs.com</a>	
TOLERANCES	NAME: Si53208-CEVB REV : 1.0	
HOLE TOLERANCES PER 78027	SIZE : B PART NUMBER: .	
DECIMALS      ANGLES      SURFACES	SCALE 1:1 FABRICATION DRAWING SHEET 1 OF 1	
.XX +/- .XXX +/-	MAX MAX MAX	
+/-	MICRONCHES	
PART TO BE FREE OF BURRS		
BREAK EDGES	BEND RADIUS	BEND RELIEF
MAX	MAX	MAX
DO NOT SCALE DRAWING		